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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

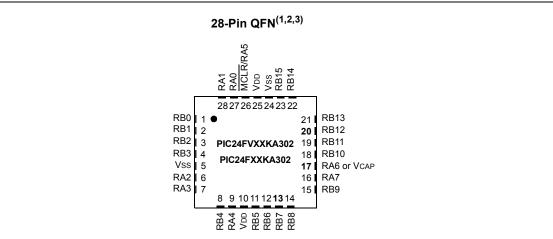
E·XFI

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I ² C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	38
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 16x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-UFQFN Exposed Pad
Supplier Device Package	48-UQFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fv32ka304-i-mv

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Pin Diagrams



D:	eatures	
Pin	PIC24FVXXKA302	PIC24FXXKA302
1	PGED1/AN2/ULPWU/CTCMP/C1IND/C2INB/C3IND/U2TX/CN4/RB0	PGED1/AN2/ULPWU/CTCMP/C1IND/C2INB/C3IND/U2TX/CN4/RB0
2	PGEC1/AN3/C1INC/C2INA/U2RX/CTED12/CN5/RB1	PGEC1/AN3/C1INC/C2INA/U2RX/CTED12/CN5/RB1
3	AN4/C1INB/C2IND/SDA2/T5CK/T4CK/U1RX/CTED13/CN6/RB2	AN4/C1INB/C2IND/SDA2/T5CK/T4CK/U1RX/CTED13/CN6/RB2
4	AN5/C1INA/C2INC/SCL2/CN7/RB3	AN5/C1INA/C2INC/SCL2/CN7/RB3
5	Vss	Vss
6	OSCI/AN13/CLKI/CN30/RA2	OSCI/AN13/CLKI/CN30/RA2
7	OSCO/AN14/CLKO/CN29/RA3	OSCO/AN14/CLKO/CN29/RA3
8	SOSCI/AN15/U2RTS/CN1/RB4	SOSCI/AN15/U2RTS/CN1/RB4
9	SOSCO/SCLKI/U2CTS/CN0/RA4	SOSCO/SCLKI/U2CTS/CN0/RA4
10	Vdd	VDD
11	PGED3/ASDA1 ⁽²⁾ /SCK2/CN27/RB5	PGED3/ASDA1 ⁽²⁾ /SCK2/CN27/RB5
12	PGEC3/ASCL1 ⁽²⁾ /SDO2/CN24/RB6	PGEC3/ASCL1 ⁽²⁾ /SDO2/CN24/RB6
13	U1TX/C2OUT/OC1/INT0/CN23/RB7	U1TX/INT0/CN23/RB7
14	SCL1/U1CTS/C3OUT/CTED10/CN22/RB8	SCL1/U1CTS/C3OUT/CTED10/CN22/RB8
15	SDA1/T1CK/U1RTS/IC2/CTED4/CN21/RB9	SDA1/T1CK/U1RTS/IC2/CTED4/CN21/RB9
16	SDI2/IC1/CTED3/CN9/RA7	SDI2/IC1/CTED3/CN9/RA7
17	VCAP	C2OUT/OC1/CTED1/INT2/CN8/RA6
18	PGED2/SDI1/OC3/CTED11/CN16/RB10	PGED2/SDI1/OC3/CTED11/CN16/RB10
19	PGEC2/SCK1/OC2/CTED9/CN15/RB11	PGEC2/SCK1/OC2/CTED9/CN15/RB11
20	AN12/HLVDIN/SS2/IC3/CTED2/INT2/CN14/RB12	AN12/HLVDIN/SS2/IC3/CTED2/CN14/RB12
21	AN11/SDO1/OCFB/CTPLS/CN13/RB13	AN11/SDO1/OCFB/CTPLS/CN13/RB13
22	CVREF/AN10/C3INB/RTCC/C1OUT/OCFA/CTED5/INT1/CN12/ RB14	CVREF/AN10/C3INB/RTCC/C1OUT/OCFA/CTED5/INT1/CN12/ RB14
23	AN9/C3INA/T3CK/T2CK/REFO/SS1/CTED6/CN11/RB15	AN9/C3INA/T3CK/T2CK/REFO/SS1/CTED6/CN11/RB15
24	Vss/AVss	Vss/AVss
25	Vdd/AVdd	Vdd/AVdd
26	MCLR/Vpp/RA5	MCLR/Vpp/RA5
27	VREF+/CVREF+/AN0/C3INC/CTED1/CN2/RA0	VREF+/CVREF+/AN0/C3INC/CN2/RA0
28	CVREF-/VREF-/AN1/CN3/RA1	CVREF-/VREF-/AN1/CN3/RA1

Legend: Pin numbers in **bold** indicate pin function differences between PIC24FV and PIC24F devices.

Note 1: Exposed pad on underside of device is connected to Vss.

2: Alternative multiplexing for SDA1 (ASDA1) and SCL1 (ASCL1) when the I2CSEL Configuration bit is set.

3: PIC24F32KA304 device pins have a maximum voltage of 3.6V and are not 5V tolerant.

TABLE 1-3: PIC24FV32KA304 FAMILY PINOUT DESCRIPTIONS (CONTINUED)

		F					FV						
		Pin Number					Pin Number						
Function	20-Pin PDIP/ SSOP/ SOIC	28-Pin SPDIP/ SSOP/ SOIC	28-Pin QFN	44-Pin QFN/ TQFP	48-Pin UQFN	20-Pin PDIP/ SSOP/ SOIC	28-Pin SPDIP/ SSOP/ SOIC	28-Pin QFN	44-Pin QFN/ TQFP	48-Pin UQFN	I/O	Buffer	Description
RA0	2	2	27	19	21	2	2	27	19	21	I/O	ST	PORTA Pins
RA1	3	3	28	20	22	3	3	28	20	22	I/O	ST	
RA2	7	9	6	30	33	7	9	6	30	33	I/O	ST	
RA3	8	10	7	31	34	8	10	7	31	34	I/O	ST	
RA4	10	12	9	34	37	10	12	9	34	37	I/O	ST	
RA5	1	1	26	18	19	1	1	26	18	19	I/O	ST	
RA6	14	20	17	7	7	_	_	—	_	_	I/O	ST	
RA7	_	19	16	6	6	_	19	16	6	6	I/O	ST	
RA8	_	_		32	35	_	_	—	32	35	I/O	ST	
RA9	_	_		35	38	_	_	—	35	38	I/O	ST	
RA10	_	_		12	13	_	_	—	12	13	I/O	ST	
RA11	_	_		13	14	_	_	—	13	14	I/O	ST	
RB0	4	4	1	21	23	4	4	1	21	23	I/O	ST	PORTB Pins
RB1	5	5	2	22	24	5	5	2	22	24	I/O	ST	
RB2	6	6	3	23	25	6	6	3	23	25	I/O	ST	
RB3	_	7	4	24	26	_	7	4	24	26	I/O	ST	
RB4	9	11	8	33	36	9	11	8	33	36	I/O	ST	
RB5	_	14	11	41	45	_	14	11	41	45	I/O	ST	
RB6	_	15	12	42	46	_	15	12	42	46	I/O	ST	
RB7	11	16	13	43	47	11	16	13	43	47	I/O	ST	
RB8	12	17	14	44	48	12	17	14	44	48	I/O	ST	
RB9	13	18	15	1	1	13	18	15	1	1	I/O	ST	
RB10	_	21	18	8	9	_	21	18	8	9	I/O	ST	
RB11	_	22	19	9	10	_	22	19	9	10	I/O	ST	
RB12	15	23	20	10	11	15	23	20	10	11	I/O	ST	
RB13	16	24	21	11	12	16	24	21	11	12	I/O	ST	
RB14	17	25	22	14	15	17	25	22	14	15	I/O	ST	
RB15	18	26	23	15	16	18	26	23	15	16	I/O	ST	

4.3.2 DATA ACCESS FROM PROGRAM MEMORY AND DATA EEPROM MEMORY USING TABLE INSTRUCTIONS

The TBLRDL and TBLWTL instructions offer a direct method of reading or writing the lower word of any address within the program memory without going through data space. It also offers a direct method of reading or writing a word of any address within data EEPROM memory. The TBLRDH and TBLWTH instructions are the only method to read or write the upper 8 bits of a program space word as data.

Note:	The TBLRDH and TBLWTH instructions are
	not used while accessing data EEPROM
	memory.

The PC is incremented by two for each successive 24-bit program word. This allows program memory addresses to directly map to data space addresses. Program memory can thus be regarded as two 16-bit word-wide address spaces, residing side by side, each with the same address range. TBLRDL and TBLWTL access the space which contains the least significant data word, and TBLRDH and TBLWTH access the space which contains the upper data byte.

Two table instructions are provided to move byte or word-sized (16-bit) data to and from program space. Both function as either byte or word operations.

- TBLRDL (Table Read Low): In Word mode, it maps the lower word of the program space location (P<15:0>) to a data address (D<15:0>).
 In Byte mode, either the upper or lower byte of the lower program word is mapped to the lower byte of a data address. The upper byte is selected when byte select is '1'; the lower byte is selected when it is '0'.
- TBLRDH (Table Read High): In Word mode, it maps the entire upper word of a program address (P<23:16>) to a data address. Note that D<15:8>, the 'phantom' byte, will always be '0'.

In Byte mode, it maps the upper or lower byte of the program word to D<7:0> of the data address, as above. Note that the data will always be '0' when the upper 'phantom' byte is selected (Byte Select = 1).

5.2 RTSP Operation

The PIC24F Flash program memory array is organized into rows of 32 instructions or 96 bytes. RTSP allows the user to erase blocks of 1 row, 2 rows and 4 rows (32, 64 and 128 instructions) at a time, and to program one row at a time. It is also possible to program single words.

The 1-row (96 bytes), 2-row (192 bytes) and 4-row (384 bytes) erase blocks, and single row write block (96 bytes) are edge-aligned from the beginning of program memory.

When data is written to program memory using TBLWT instructions, the data is not written directly to memory. Instead, data written using table writes is stored in holding latches until the programming sequence is executed.

Any number of TBLWT instructions can be executed and a write will be successfully performed. However, 32 TBLWT instructions are required to write the full row of memory.

The basic sequence for RTSP programming is to set up a Table Pointer, then do a series of TBLWT instructions to load the buffers. Programming is performed by setting the control bits in the NVMCON register.

Data can be loaded in any order and the holding registers can be written to multiple times before performing a write operation. Subsequent writes, however, will wipe out any previous writes.

Note: Writing to a location multiple times without erasing it is not recommended.

All of the table write operations are single-word writes (two instruction cycles), because only the buffers are written. A programming cycle is required for programming each row.

5.3 Enhanced In-Circuit Serial Programming

Enhanced ICSP uses an on-board bootloader, known as the Programming Executive (PE), to manage the programming process. Using an SPI data frame format, the Programming Executive can erase, program and verify program memory. For more information on Enhanced ICSP, see the device programming specification.

5.4 Control Registers

There are two SFRs used to read and write the program Flash memory: NVMCON and NVMKEY.

The NVMCON register (Register 5-1) controls the blocks that need to be erased, which memory type is to be programmed and when the programming cycle starts.

NVMKEY is a write-only register that is used for write protection. To start a programming or erase sequence, the user must consecutively write 55h and AAh to the NVMKEY register. For more information, refer to **Section 5.5 "Programming Operations"**.

5.5 Programming Operations

A complete programming sequence is necessary for programming or erasing the internal Flash in RTSP mode. During a program or erase operation, the processor stalls (Waits) until the operation is finished. Setting the WR bit (NVMCON<15>) starts the operation and the WR bit is automatically cleared when the operation is finished.

REGISTER 8-10: IFS5: INTERRUPT FLAG STATUS REGISTER 5

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
_	—	—	—	—	—	_	—
bit 15			•		•		bit 8
U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0, HS
_	_	—	—	—	—	_	ULPWUIF
bit 7							bit 0
l edenq.		HS = Hardwa	re Settable bit				

Legend:	HS = Hardware Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	d as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-1 Unimplemented: Read as '0'

bit 0 ULPWUIF: Ultra Low-Power Wake-up Interrupt Flag Status bit

1 = Interrupt request has occurred

0 = Interrupt request has not occurred

REGISTER	8-17: IPC0	: INTERRUPT	PRIORITY (CONTROL RI	EGISTER 0		
U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	T1IP2	T1IP1	T1IP0	—	OC1IP2	OC1IP1	OC1IP0
bit 15							bit 8
U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
	IC1IP2	IC1IP1	IC1IP0		INT0IP2	INT0IP1	INTOIPO
bit 7							bit 0
Logondu							
Legend:	la hit	VV - VVritabla I	.:+		nantad hit raa	d aa 'O'	
R = Readab		W = Writable I	אנ	-	nented bit, rea		
-n = Value a	t POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	iown
bit 15	Unimpleme	nted: Read as 'o	,				
bit 14-12	T1IP<2:0>: ⊺	Timer1 Interrupt	Priority bits				
	111 = Interru	upt is Priority 7 (ł	nighest priority	interrupt)			
	•						
	•						
		upt is Priority 1 upt source is disa	bled				
bit 11		nted: Read as '0					
bit 10-8	-	: Output Compa		nterrunt Priorit	v bite		
DIL 10-0		upt is Priority 7 (I			y bits		
	•		lightest phoney	interrupt)			
	•						
	001 = Interru	upt is Priority 1					
		upt source is disa					
bit 7	Unimpleme	nted: Read as '0	3				
bit 6-4	IC1IP<2:0>:	Input Capture C	hannel 1 Inter	rupt Priority bit	S		
	111 = Interru	upt is Priority 7 (ł	nighest priority	interrupt)			
	•						
	• 001 – Intorr i	upt is Priority 1					
		upt source is disa	abled				
bit 3		nted: Read as '0					
bit 2-0	-	: External Intern		its			
5112 0		upt is Priority 7 (I					
	•						
	•						
		upt is Priority 1 upt source is disa					

11.1.1 OPEN-DRAIN CONFIGURATION

In addition to the PORT, LAT and TRIS registers for data control, each port pin can also be individually configured for either digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The maximum open-drain voltage allowed is the same as the maximum V_{IH} specification.

11.2 Configuring Analog Port Pins

The use of the ANS and TRIS registers control the operation of the A/D port pins. The port pins that are desired as analog inputs must have their corresponding TRISx bit set (input). If the TRISx bit is cleared (output), the digital output level (VOH or VOL) will be converted.

When reading the PORT register, all pins configured as analog input channels will read as cleared (a low level). Analog levels on any pin that is defined as a digital input (including the ANx pins) may cause the input buffer to consume current that exceeds the device specifications.

11.2.1 ANALOG SELECTION REGISTERS

I/O pins with shared analog functionality, such as A/D inputs and comparator inputs, must have their digital inputs shut off when analog functionality is used. Note that analog functionality includes an analog voltage being applied to the pin externally.

To allow for analog control, the ANSx registers are provided. There is one ANS register for each port (ANSA, ANSB and ANSC). Within each ANSx register, there is a bit for each pin that shares analog functionality with the digital I/O functionality.

If a particular pin does not have an analog function, that bit is unimplemented. See Register 11-1 to Register 11-3 for implementation.

REGISTER 11-1: ANSA: ANALOG SELECTION (PORTA)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8
U-0	U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1
	—	-	—	ANSA3	ANSA2	ANSA1	ANSA0
bit 7							bit 0
Legend:							
R = Readable	R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'						
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cleared x = Bit is unknown			nown

bit 15-4 Unimplemented: Read as '0'

bit 3-0 ANSA<3:0>: Analog Select Control bits

1 = Digital input buffer is not active (use for analog input)

0 = Digital input buffer is active

EQUATION 16-1: RELATIONSHIP BETWEEN DEVICE AND SPIX CLOCK SPEED⁽¹⁾

FCY

FSCK = Primary Prescaler * Secondary Prescaler

Note 1: Based on FCY = FOSC/2; Doze mode and PLL are disabled.

TABLE 16-1: SAMPLE SCKx FREQUENCIES^(1,2)

Fcy = 16 MHz	Secondary Prescaler Settings						
		1:1	2:1	4:1	6:1	8:1	
Primary Prescaler Settings	1:1	Invalid	8000	4000	2667	2000	
	4:1	4000	2000	1000	667	500	
	16:1	1000	500	250	167	125	
	64:1	250	125	63	42	31	
Fcy = 5 MHz							
Primary Prescaler Settings	1:1	5000	2500	1250	833	625	
	4:1	1250	625	313	208	156	
	16:1	313	156	78	52	39	
	64:1	78	39	20	13	10	

Note 1: Based on Fcy = Fosc/2; Doze mode and PLL are disabled.

2: SCKx frequencies are indicated in kHz.

REGISTER 26-10: DEVREV: DEVICE REVISION REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 23							bit 16
U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15	•	-				•	bit 8
U-0	U-0	U-0	U-0	R	R	R	R
—		—	—	REV3	REV2	REV1	REV0
bit 7	•	-				•	bit 0
Legend:							
R = Readable bit W = Writable bit				U = Unimplem	ented bit, read	l as '0'	
-n = Value at POR (1' = Bit is set				'0' = Bit is cleared x = Bit is unknown			nown

bit 23-4 Unimplemented: Read as '0'

bit 3-0 **REV<3:0>:** Minor Revision Identifier bits

TABLE 28-1: SYMBOLS USED IN OPCODE DESCRIPTIONS

Field	Description
#text	Means literal defined by "text"
(text)	Means "content of text"
[text]	Means "the location addressed by text"
{ }	Optional field or operation
<n:m></n:m>	Register bit field
.b	Byte mode selection
.d	Double-Word mode selection
.S	Shadow register select
.W	Word mode selection (default)
bit4	4-bit bit selection field (used in word addressed instructions) $\in \{015\}$
C, DC, N, OV, Z	MCU Status bits: Carry, Digit Carry, Negative, Overflow, Sticky Zero
Expr	Absolute address, label or expression (resolved by the linker)
f	File register address ∈ {0000h1FFFh}
lit1	1-bit unsigned literal $\in \{0,1\}$
lit4	4-bit unsigned literal $\in \{015\}$
lit5	5-bit unsigned literal $\in \{031\}$
lit8	8-bit unsigned literal $\in \{0255\}$
lit10	10-bit unsigned literal ∈ {0255} for Byte mode, {0:1023} for Word mode
lit14	14-bit unsigned literal ∈ {016384}
lit16	16-bit unsigned literal ∈ {065535}
lit23	23-bit unsigned literal ∈ {08388608}; LSB must be '0'
None	Field does not require an entry, may be blank
PC	Program Counter
Slit10	10-bit signed literal ∈ {-512511}
Slit16	16-bit signed literal ∈ {-3276832767}
Slit6	6-bit signed literal ∈ {-1616}
Wb	Base W register ∈ {W0W15}
Wd	Destination W register ∈ { Wd, [Wd], [Wd++], [Wd], [++Wd], [Wd] }
Wdo	Destination W register ∈ { Wnd, [Wnd], [Wnd++], [Wnd], [++Wnd], [Wnd], [Wnd+Wb] }
Wm,Wn	Dividend, Divisor working register pair (direct addressing)
Wn	One of 16 working registers \in {W0W15}
Wnd	One of 16 destination working registers \in {W0W15}
Wns	One of 16 source working registers \in {W0W15}
WREG	W0 (working register used in File register instructions)
Ws	Source W register ∈ { Ws, [Ws], [Ws++], [Ws], [++Ws], [Ws] }
Wso	Source W register ∈ { Wns, [Wns], [Wns++], [Wns], [++Wns], [Wns], [Wns+Wb] }

Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles	Status Flags Affected
TBLRDL	TBLRDL	Ws,Wd	Read Prog<15:0> to Wd	1	2	None
TBLWTH	TBLWTH	Ws,Wd	Write Ws<7:0> to Prog<23:16>	1	2	None
TBLWTL	TBLWTL	Ws,Wd	Write Ws to Prog<15:0>	1	2	None
ULNK	ULNK		Unlink Frame Pointer	1	1	None
XOR	XOR	f	f = f .XOR. WREG	1	1	N, Z
	XOR	f,WREG	WREG = f .XOR. WREG	1	1	N, Z
	XOR	#lit10,Wn	Wd = lit10 .XOR. Wd	1	1	N, Z
	XOR	Wb,Ws,Wd	Wd = Wb .XOR. Ws	1	1	N, Z
	XOR	Wb,#lit5,Wd	Wd = Wb .XOR. lit5	1	1	N, Z
ZE	ZE	Ws,Wnd	Wnd = Zero-Extend Ws	1	1	C, Z, N

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

29.2 AC Characteristics and Timing Parameters

The information contained in this section defines the PIC24FV32KA304 family AC characteristics and timing parameters.

TABLE 29-17: TEMPERATURE AND VOLTAGE SPECIFICATIONS - AC

	Standard Operating Conditions:	1.8V to 3.6V PIC24F32KA3XX
	_	2.0V to 5.5V PIC24FV32KA3XX
AC CHARACTERISTICS	Operating temperature:	-40°C \leq TA \leq +85°C for Industrial
		-40°C \leq TA \leq +125°C for Extended
	Operating voltage VDD range as des	scribed in Section 29.1 "DC Characteristics".

FIGURE 29-3: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

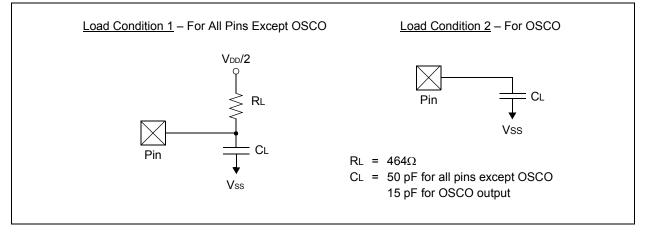
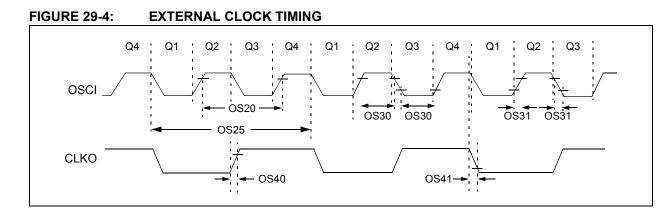


TABLE 29-18: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

Param No.	Symbol	Characteristic	Min	Typ ⁽¹⁾	Max	Units	Conditions
DO50	Cosc2	OSCO/CLKO Pin	_	—	15	pF	In XT and HS modes when the external clock is used to drive OSCI
DO56	Сю	All I/O Pins and OSCO	—	—	50	pF	EC mode
DO58	Св	SCLx, SDAx		—	400	pF	In I ² C™ mode

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.



AC CHARACTERISTICS Standard Operating Conditions: 1.8V to 3.6V PIC24F32KA3 2.0V to 5.5V PIC24FV32KA							
AC CH	ARACI	ERISTICS	Operating terr	$\begin{array}{ll} \mbox{temperature} & -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for Industrial} \\ -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ for Extended} \end{array}$			
Param No.	Sym	Characteristic	Min	Typ ⁽¹⁾ Max Units Conditions			
OS10	Fosc	External CLKI Frequency (External clocks allowed only in EC mode)	DC 4		32 8	MHz MHz	EC ECPLL
OS15		Oscillator Frequency	0.2 4 4 31	 	4 25 8 33	MHz MHz MHz kHz	XT HS XTPLL SOSC
OS20	Tosc	Tosc = 1/Fosc	—	—	_	_	See Parameter OS10 for Fosc value
OS25	TCY	Instruction Cycle Time ⁽²⁾	62.5	—	DC	ns	
OS30	TosL, TosH	External Clock in (OSCI) High or Low Time	0.45 x Tosc	—	_	ns	EC
OS31	TosR, TosF	External Clock in (OSCI) Rise or Fall Time	_	—	20	ns	EC
OS40	TckR	CLKO Rise Time ⁽³⁾	—	6	10	ns	
OS41	TckF	CLKO Fall Time ⁽³⁾	_	6	10	ns	

TABLE 29-19: EXTERNAL CLOCK TIMING REQUIREMENTS

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The instruction cycle period (TcY) equals two times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type, under standard operating conditions, with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "Min." values with an external clock applied to the OSCI/CLKI pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

3: Measurements are taken in EC mode. The CLKO signal is measured on the OSCO pin. CLKO is low for the Q1-Q2 period (1/2 TCY) and high for the Q3-Q4 period (1/2 TCY).

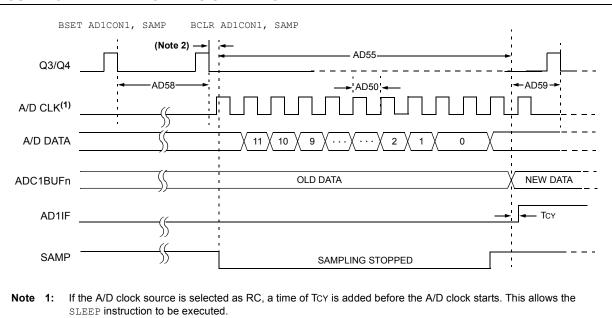


FIGURE 29-22: A/D CONVERSION TIMING

2: This is a minimal RC delay (typically 100 ns) which also disconnects the holding capacitor from the analog input.

AC CHARACTERISTICS			$\begin{tabular}{lllllllllllllllllllllllllllllllllll$					
Param No.	Symbol Characteristic		Min.	Тур	Max.	Units	Conditions	
		(Clock Pa	rameter	s			
AD50	Tad	A/D Clock Period	600	—	—	ns	Tcy = 75 ns, AD1CON3 in default state	
AD51	TRC	A/D Internal RC Oscillator Period	_	1.67	—	μs		
			Convers	ion Rate)			
AD55	TCONV	Conversion Time	_	12 14	_	Tad Tad	10-bit results 12-bit results	
AD56	FCNV	Throughput Rate	_		100	ksps		
AD57	TSAMP	Sample Time	_	1	_	Tad		
AD58	TACQ	Acquisition Time	750		_	ns	(Note 2)	
AD59	Tswc	Switching Time from Convert to Sample	_	—	(Note 3)			
AD60	TDIS	Discharge Time	12		—	Tad		
		(Clock Pa	rameter	s			
AD61	TPSS	Sample Start Delay from Setting Sample bit (SAMP)	2	_	3	Tad		

TABLE 29-41: A/D CONVERSION TIMING REQUIREMENTS⁽¹⁾

Note 1: Because the sample caps will eventually lose charge, clock rates below 10 kHz can affect linearity performance, especially at elevated temperatures.

2: The time for the holding capacitor to acquire the "New" input voltage when the voltage changes full scale after the conversion (VDD to Vss or Vss to VDD).

3: On the following cycle of the device clock.

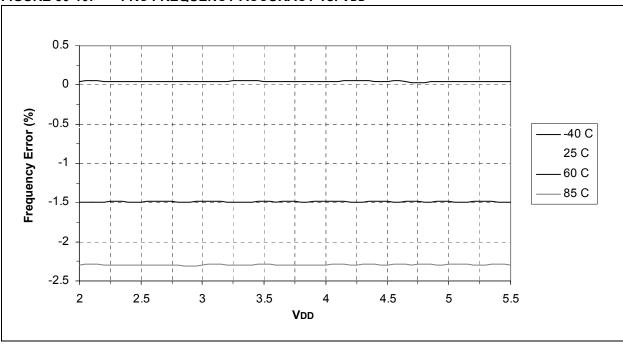


FIGURE 30-10: FRC FREQUENCY ACCURACY vs. VDD



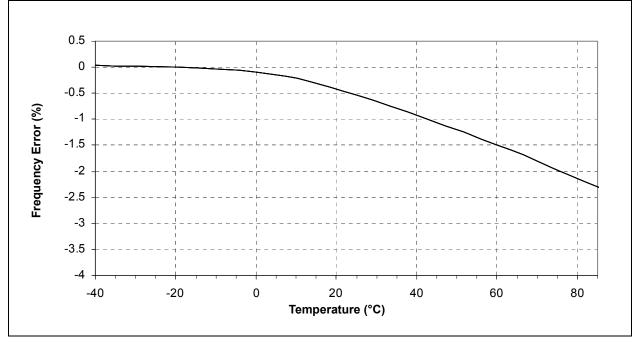


FIGURE 30-49: TYPICAL Vol vs. Iol (GENERAL I/O, $2.0V \le VDD \le 5.5V$)

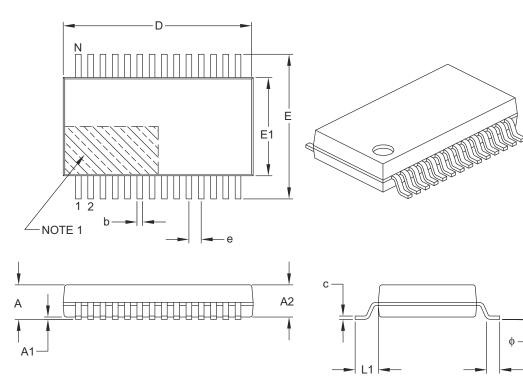
0 Γοι (MA)

FIGURE 30-50: TYPICAL VOH vs. IOH (GENERAL I/O, AS A FUNCTION OF TEMPERATURE, $2.0V \le V \text{DD} \le 5.5 \text{V})$

(л) нол	-		-	_	
		Іон (mA)			

28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units			MILLIMETERS			
Dimensio	Dimension Limits		NOM	MAX			
Number of Pins	Ν		28				
Pitch	е		0.65 BSC				
Overall Height	А	-	-	2.00			
Molded Package Thickness	A2	1.65	1.75	1.85			
Standoff	A1	0.05	-	_			
Overall Width	Е	7.40	7.80	8.20			
Molded Package Width	E1	5.00	5.30	5.60			
Overall Length	D	9.90	10.20	10.50			
Foot Length	L	0.55	0.75	0.95			
Footprint	L1	1.25 REF					
Lead Thickness	С	0.09	-	0.25			
Foot Angle	ф	0°	4°	8°			
Lead Width	b	0.22	-	0.38			

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
 Dimensioning and tolerancing per ASME Y14.5M.

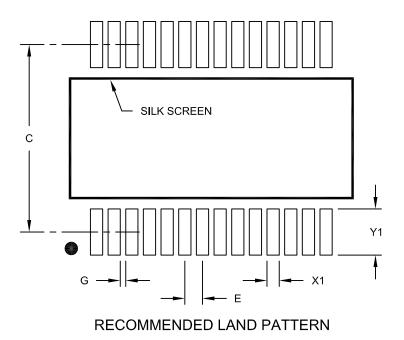
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units			S	
Dimension	Dimension Limits		NOM	MAX	
Contact Pitch	E	0.65 BSC			
Contact Pad Spacing	С		7.20		
Contact Pad Width (X28)	X1			0.45	
Contact Pad Length (X28)	Y1			1.75	
Distance Between Pads	G	0.20			

Notes:

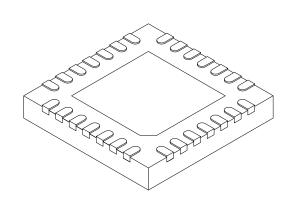
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2073A

28-Lead Plastic Quad Flat, No Lead Package (ML) - 6x6 mm Body [QFN] With 0.55 mm Terminal Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	М	MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX	
Number of Pins	N		28		
Pitch	е		0.65 BSC		
Overall Height	A	0.80	0.90	1.00	
Standoff	A1	0.00	0.02	0.05	
Terminal Thickness	A3	0.20 REF			
Overall Width	E	6.00 BSC			
Exposed Pad Width	E2	3.65	3.70	4.20	
Overall Length	D	6.00 BSC			
Exposed Pad Length	D2	3.65	3.70	4.20	
Terminal Width	b	0.23	0.30	0.35	
Terminal Length	L	0.50	0.55	0.70	
Terminal-to-Exposed Pad	K	0.20	-	-	

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. Package is saw singulated

3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances. REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-105C Sheet 2 of 2

NOTES: